



EVG[®]101

Advanced Resist Processing System



Introduction

Single-wafer resist processing in R&D and small-scale production

The EVG101 resist processing system performs R&D-type processes on a single chamber design, which is fully compatible with EVG's automated systems. The EVG101 supports wafers up to 300 mm and can be configured for spin or spray coating and developing. Conformal layers of photoresist or polymers are achieved on 3D structured wafers for interconnection techniques with EVG's advanced OmniSpray coating technology. This ensures low material consumption of precious high-viscosity photoresists or polymers while improving uniformity and resist spreading options.

| Technical Data | |
|---------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Wafer diameter (substrate size) | up to 300 mm |
| Available modules | - Spin coat / OmniSpray [®] / develop |
| Wafer handling options | - Single / double EE / edge handling / wafer flipping - Bowed / warped / thin wafer handling |
| Dispense options | - various resist dispense pumps to cover a wide range of viscosities up to 52000 cP - constant pressure dispense systems - EBR / BSR / pre-wet / bowl wash / liquid priming |

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Features

- Wafer size up to 300 mm
- Automated spin or spray coating or developing with manual wafer load/unload
- Quick and easy process transfer from research to production utilizing proven modular design and standardized software
- Syringe dispense system for utilization of small resist volumes, including high-viscosity resists
- Small footprint while maintaining a high level of personal and process safety
- Multi-user concept (unlimited number of user accounts and recipes, assignable access rights, different user interface languages)
- Options:
 - Uniform coating of high-topography wafer surfaces with OmniSpray[®] coating technology
 - Wax and epoxy coating for subsequent bonding processes
 - Spin-On-Glass (SOG) coating

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